filling the through-hole with a thermosetting conductive substance so as to form a second sheet having the through-hole filled with the thermosetting conductive substance;

mounting a circuit component on a first film;

positioning and superimposing the second sheet on the side of the first film where the circuit component is mounted, and superimposing a second film having a wiring pattern portion on the second sheet, thereby forming a third sheet in which the circuit component is buried; and

heating the third sheet so as to form a fourth sheet in which the thermosetting resin and the conductive substance are cured.

11. (Amended) A method for producing a circuit component built-in module comprising the steps of:

processing a mixture comprising 70wt% to 95wt% of an inorganic filler and an uncured thermosetting resin into a first sheet having a through-hole;

filling the through-hole with a thermosetting conductive substance so as to form a second sheet having the through-hole filled with the thermosetting conductive substance;

mounting a circuit component on a first film;

positioning and superimposing the second sheet on the side of the first film where the circuit component is mounted, and superimposing a second film having a wiring pattern portion on the second sheet, thereby forming a third sheet in which the circuit component is buried; and

heating the third sheet so as to form a fourth sheet in which the thermosetting resin and the conductive substance are cured , wherein the first and second films are formed of copper foils, and the method further comprises a step of removing a portion of the copper foils so as to form wiring patterns on which the circuit component is mounted, said step of removing the copper foils is after the step of heating the third sheet so as to form ~~the step of forming~~ the fourth sheet.

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~~18~~. (Amended) The method for producing a circuit component built-in module according to claim ~~15~~ 11, wherein the first and second films are formed of release films having wiring patterns formed on one principal plane thereof, and the method further comprises a step of peeling the release films from the fourth sheet, said step of peeling the release films is after the step of heating the third sheet so as to form ~~the step of forming~~ the fourth sheet, and the circuit component is mounted on the wiring patterns of the first film.

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~~22~~. (Amended) The method for producing a circuit component built-in module according to claim ~~18~~ 1, wherein the step of processing the mixture into the first sheet comprises a step of forming the mixture into a sheet mixture and a step of heating the sheet mixture at a temperature below a cure temperature of the thermosetting resin, thereby eliminating adhesion of the sheet mixture.

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~~23~~. (Amended) The method for producing a circuit component built-in module according to claim ~~15~~ 1, wherein the step of positioning and superimposing to form the third sheet by burying the circuit component in the second sheet is performed at a temperature below a cure temperature of the thermosetting resin.

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~~28~~. (Amended) The method for producing a circuit component built-in module according to claim ~~26~~ 12, wherein the film including the wiring pattern portion is formed of a copper foil, and the method further comprises a step of removing the copper foil in a portion other than the wiring pattern portion so as to form a wiring pattern, said step of removing the copper foil is after the step of pressing and heating to form the fifth sheet.

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~~29~~. (Amended) The method for producing a circuit component built-in module according to claim ~~26~~ 12, wherein the film including the wiring pattern portion is formed of a

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release film having a wiring pattern formed on one principal plane thereof, and the method further comprises a step of peeling the release film from the fifth sheet, said step of peeling the release film is after a step of pressing and heating to form the fifth sheet.

~~20~~ ~~33~~. (Amended) The method for producing a circuit component built-in module according to claim ~~26~~ 12, wherein the step of processing the mixture into the first sheet further comprises a step of heating the sheet mixture at a temperature below a cure temperature of the thermosetting resin, thereby eliminating adhesion of the sheet mixture, said step of heating the sheet mixture is after the step of processing the mixture into the sheet.

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~~34~~ 21. (Amended) The method for producing a circuit component built-in module according to claim ~~26~~ 12, wherein the step of positioning and superimposing to form the third sheet by burying the circuit component in the second sheet is performed at a temperature below a cure temperature of the thermosetting resin.